

【Causes/processes involved/keys to judgment】

The center of a laser drilled via-hole is misaligned from the center of the via-bottom-land. The laser drilled hole pierces the layer of via-bottom-land and reaches the next layer. Copper deposits on this hole nearly reaching to the next layer. (Exposure, lamination, laser-drilling and through hole plating processes)

1-8-4-19 回路形状不適短絡／线路设计不合理的短路 / Short by improper conductive pattern

【特徴】 回路の形状設計が不適切な部分に出来た短絡

【特征】 线路的形状设计不合理所引起的短路。

【Characteristics】 Short occurring at the area where the conductive pattern design is not appropriate

【原因・判断ポイント・発生工程】 E T液の流れを阻害するような回路形状部に、E T液が旨く流れなかったために出来たE T不足短絡

【原因、判断要点、发生工序】 线路的形状妨碍 ET 液的流动，致使 ET 液的流动不畅，ET 不足的短路。

【Causes/processes involved/keys to judgment】

Insufficient etching is caused by retarded etching speed at the conductor portion where the pattern design is not appropriate. Etchant cannot flow smoothly into the area due to an improper conductor shape.



【コメント】
顕微鏡倍率 ×

【注釋】
显微镜倍率 ×

【Comments】
Magnification: ×

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